

L Number	Hits	Search Text	DB	Time stamp
166	1240	((flexible near1 (film board substrate carrier tape)) and (flipchip (flip adj chip)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/09/15 15:27
167	291	((flexible near1 (film board substrate carrier tape)) and (flipchip (flip adj chip))) and (solder adj (resist mask))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/09/15 15:28
168	10525	control\$3 with (flowing flow) with (underfill\$3 resin sealing)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/09/15 15:32
169	0	((flexible near1 (film board substrate carrier tape)) and (flipchip (flip adj chip))) and (solder adj (resist mask)); and (control\$3 with (flowing flow) with (underfill\$3 resin sealing))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/09/15 15:30
170	4	((flexible near1 (film board substrate carrier tape)) and (flipchip (flip adj chip))) and (control\$3 with (flowing flow) with (underfill\$3 resin sealing))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/09/15 15:30
171	35	((flexible near1 (film board substrate carrier tape)) and (flipchip (flip adj chip))) and (solder adj (resist mask)); and ((flowing flow) with (underfill\$3 resin sealing))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/09/15 15:32